

**IN THE CLAIMS:**

Please amend claims 1-5 on substitute pages 5 and 6 to read as follows:

5 --1. (Amended) A device for placing flip chips on a substrate in the form  
of a leadframe, the device comprising a movable placement head, which picks up the  
flip chips from a stock of components and places them on the substrate, the  
placement head being provided with a turning device for the flip chips, the placement  
head being provided with a multiplicity of grippers circulating in a turret-like indexed  
manner, the turning device being assigned to a stationary part of the placement head,  
the turning device taking one of the flip chips in a first holding station of the grippers  
10 and after turning the chip, returning the turned chip to one of the grippers in one of  
the downstream holding stations.--

15 --2. (Amended) The device as claimed in claim 1, wherein the turning  
device has two pivotable holders, one of the two holders can be aligned with the first  
of the holding stations, and a second holder of the two holders can be aligned with  
a downstream one of the holding stations and wherein the two holders can be  
pivoted into a mutual transfer position, in which their ends, carrying the flip chip and  
projecting toward each other, are aligned with each other.--

20 --3. (Amended) The device as claimed in claim 2, wherein the holders are  
designed as pivotably mounted suction pipettes, wherein the grippers are designed  
as suction grippers protruding radially from the placement head, wherein the holders  
have pivoting axes extending perpendicular to a turning plane of the grippers and  
being arranged on axial extensions of the grippers and wherein longitudinal axes of  
the holders and of the grippers are in line with one another during the transfer of the  
flip chips therebetween.--

A1  
--4. (Amended) The device as claimed in claim 3, wherein a clearance between the holders directed oppositely facing each other and in line with each other in the transfer position is somewhat larger than the thickness of the flip chips.--

5 --5. (Amended) The device as claimed in claim 4, wherein the first and downstream holding stations are arranged immediately following each other.--

Please add the following claims:

--6. A device according to claim 3, wherein the first and downstream holding stations are arranged immediately following one another.--

A2  
10 --7. A device according to claim 2, wherein a clearance between the holders while facing each other in the transfer position is larger than the thickness of the flip chips.--

--8. A device according to claim 7, wherein the first and downstream holding stations are arranged immediately following each other.--

15 --9. A device according to claim 2, wherein the downstream holding station is arranged to immediately follow the first holding station.--

--10. A device according to claim 1, wherein the downstream holding station immediately follows the first holding station.--